

SC13154MP

Claim Amendments

1. (currently amended) A method of packaging an integrated circuit die, comprising the steps of:

providing a foil sheet;

forming a single layer of solder on a first side of the foil sheet;

attaching a first side of an integrated circuit die to the single solder layer on the foil sheet, wherein the first side of the die includes a layer of metal thereon and a second, opposing side of the die includes a plurality of bonding pads;

electrically connecting the bonding pads to the single solder layer on the foil sheet with a plurality of wires;

encapsulating the die, the electrical connections, and the first side of the foil sheet with a mold compound; and

separating the foil sheet from the die and the plurality of wires, thereby forming a packaged integrated circuit.

2. (original) The method of packaging an integrated circuit according to claim 1, wherein the foil sheet comprises a bare metal sheet.

3. (original) The method of packaging an integrated circuit according to claim 2, wherein the metal sheet comprises one of copper and aluminum.

4. (original) The method of packaging an integrated circuit according to claim 1, wherein the solder is formed on the foil sheet via a screen printing process.